

WHAT IS CLAIMED IS:

1. A method for manufacturing a printed circuit board comprising:
washing a land that corresponds to an exposed portion of a copper
5 circuit of a printed circuit board with acidic electrolytic water having a pH of
not more than 5 to remove an oxide;
treating the land with basic electrolytic water having a pH of not
less than 9 to prevent oxidation; and
soldering electronic components to the land.
- 10 2. The method according to claim 1, wherein the acidic electrolytic
water has a pH of not more than 4.
- 15 3. The method according to claim 2, wherein the acidic electrolytic
water has a pH of not more than 3.
4. The method according to claim 1, wherein the basic electrolytic
water has a pH of not less than 10.
- 20 5. The method according to claim 4, wherein the basic electrolytic
water has a pH of not less than 11.
6. The method according to claim 1, wherein application of the acidic
electrolytic water or the basic electrolytic water to the land is performed by
25 spraying.
7. The method according to claim 1, wherein application of the acidic
electrolytic water or the basic electrolytic water to the land is performed by
immersion.
- 30 8. The method according to claim 1, wherein washing with the acidic
electrolytic water and oxidation prevention with the basic electrolytic water
are performed successively as a pretreatment before soldering electronic
components to the printed circuit board.
- 35 9. The method according to claim 1 wherein, the acidic electrolytic
water that has been used for washing and the basic electrolytic water that

has been used for oxidation prevention are mixed and drained.

10. The method according to claim 9, wherein the acidic electrolytic water and the basic electrolytic water are mixed to create neutral water, and
5 the neutral water is drained.

11. The method according to claim 1, wherein the land of the printed circuit board is a copper plated land that surrounds a through hole provided in a substrate.

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12. The method according to claim 1, wherein the land of the printed circuit board is a land on which an electronic component or semiconductor is mounted.